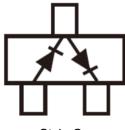




DESCRIPTION

The MMBD7000 is available in SOT-23 package.



Style C

ORDERING INFORMATION

| Package Type | Part Number | | |
|--|--------------------|--|--|
| SOT-23 | MMBD7000 | | |
| Note | SPQ: 3,000pcs/Reel | | |
| AiT provides all RoHS Compliant Products | | | |

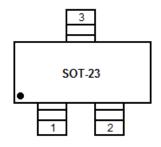
FEATURES

- Fast Switching Speed
- Surface Mount Package Ideally Suited for Automatic Insertion
- For General Purpose Switching Applications
- High Conductance
- Available in SOT-23 package

MECHANICAL DATA

Case: SOT-23, Molded Plastic Case material-UL Flammability Rating Classification 94V-0 Moisture sensitivity: Level 1 per J-STD-020A Terminals: Solder per MIL-STD-202, Method 208 Polarity: See Diagram Weight: 0.008 grams (approx.)

PIN DESCRIPTION







ABSOLUTE MAXIMUM RATINGS

| T _A = 25°C, unless otherwise specified | | |
|---|--------------------------------|-----------------------------------|
| V _{RM} , Non-Repetitive Peak Reverse Voltage | | 100V |
| V _{RRM} , Peak Repetitive Reverse Voltage | | |
| V _{RWM} , Working Peak Reverse Voltage | 75V | |
| V _R , DC Blocking Voltage | | |
| V _{R(RMS)} , RMS Reverse Voltage | | 53V |
| IFM, Forward Continuous Current ^{NOTE1} | | 300mA |
| | @ t = 1.0µs | 2.0A |
| IFSM, Non-Repetitive Peak Forward Surge Current | @ t = 1.0s | 1.0A |
| P _D , Power Dissipation NOTE1 | | 350mW |
| $R_{\theta JA,}$ Thermal Resistance Junction to Ambient Air $^{\text{NOTE1}}$ | | 357°C/W |
| TJ, TSTG, Operating and Storage Temperature Range | | -65°C ~ +150°C |
| Stresses above may cause permanent damage to the device. These ar | a atraca ratinga only and fund | tional operation of the device of |

Stresses above may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated in the Electrical Characteristics are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

T_A= 25°C, unless otherwise specified

| Parameter | Symbol | Characteristic | Min | Max | Unit |
|----------------------------------|-------------------|--|------|------|------|
| Reverse Breakdown VoltageNOTE2 | V _(BR) | I _R = 100μA | 75 | - | V |
| Forward Voltage ^{NOTE2} | VF | I _F = 1.0mA | 0.55 | 0.70 | V |
| | | I _F = 10mA | 0.67 | 0.82 | |
| | | I _F = 50mA | 0.75 | 1.10 | |
| | | I _F = 150mA | - | 1.25 | |
| Reverse Current | IR | V _R = 50V | - | 1.0 | μA |
| | | V _R = 100V | - | 3.0 | μA |
| | | V _R = 50V, T _J = 125°C | - | 100 | μA |
| | | V _R = 20V | - | 25 | nA |
| Total Capacitance | Ст | V _R = 0V, f = 1.0MHz | - | 2.0 | pF |
| Reverse Recovery Time | trr | $I_F = I_R = 10mA$ | - | 4.0 | ns |
| | | $I_{rr} = 0.1 \text{ x } I_{R}, R_{L} = 100\Omega$ | | | |

NOTE1: Part mounted on FR-4 board with recommended pad layout.

NOTE2: Short duration test pulse used to minimize self-heating effect.





TYPICAL PERFORMANCE CHARACTERISTICS

Figure. 1 Forward Characteristics

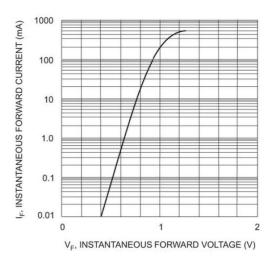


Figure. 3 Power Dissipation Derating

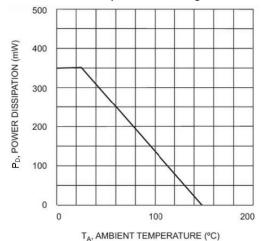
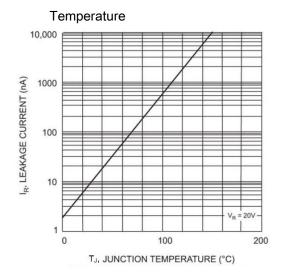


Figure. 2 Leakage Current vs. Junction

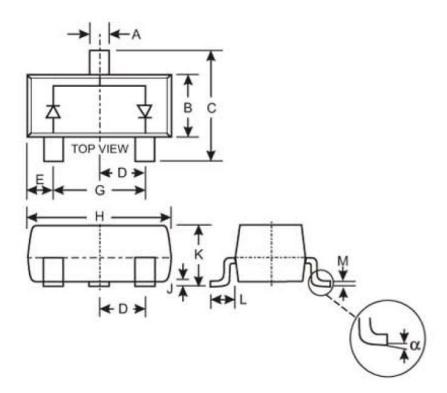






PACKAGE INFORMATION

Dimension in SOT-23 Package (Unit: mm)



| DIM | MIN | MAX |
|-----|-------|------|
| А | 0.37 | 0.51 |
| В | 1.20 | 1.40 |
| С | 2.30 | 2.50 |
| D | 0.89 | 1.03 |
| E | 0.45 | 0.60 |
| G | 1.78 | 2.05 |
| Н | 2.80 | 3.00 |
| J | 0.013 | 0.10 |
| К | 0.903 | 1.10 |
| L | 0.45 | 0.61 |
| М | 0.85 | 0.80 |
| α | 0° | 8° |



IMPORTANT NOTICE

AiT Semiconductor Inc. (AiT) reserves the right to make changes to any its product, specifications, to discontinue any integrated circuit product or service without notice, and advises its customers to obtain the latest version of relevant information to verify, before placing orders, that the information being relied on is current.

AiT Semiconductor Inc.'s integrated circuit products are not designed, intended, authorized, or warranted to be suitable for use in life support applications, devices or systems or other critical applications. Use of AiT products in such applications is understood to be fully at the risk of the customer. As used herein may involve potential risks of death, personal injury, or servere property, or environmental damage. In order to minimize risks associated with the customer's applications, the customer should provide adequate design and operating safeguards.

AiT Semiconductor Inc. assumes to no liability to customer product design or application support. AiT warrants the performance of its products of the specifications applicable at the time of sale.